Single 2-Input OR Gate

General Description

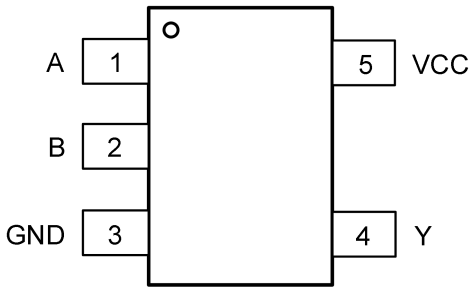
The ETQ74LVC1G32 is a single 2-input OR Gate in three tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

Features

- Designed for 1.65V to 5.5V V_{CC} Operation
- Over-voltage Tolerant Inputs Accept Voltages to 5.5V
- ±32mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- These Devices are Pb-Free and RoHS Compliant
- Multiple Package Options Automotive AEC-Q100 Grade 1 Qualified
  -- Ambient Temperature Range of -40°C to 125°C
  -- ESD HBM ±4KV PASS
  -- ESD CDM ±1KV PASS
  -- Latch Up Current to ±100mA PASS
- Part No. and Package Information

Part No.	Package	Packing Option	MSL
ETQ74LVC1G32	SC70-5 (1.3mm × 2.1mm)	Tape and Reel, 3K/Reel	1
ETQ74LVC1G32T	SOT23-5 (1.6mm × 2.9mm)	Tape and Reel, 3K/Reel	1

Pin Configuration



SC70-5/SOT23-5

Figure1. Pin Configuration

Pin Function

SC70-5/SOT23-5

Pin No.	Pin Name	Function
1	A	Input A
2	B	Input B
3	GND	Ground
4	Y	Output Y
5	VCC	Supply Voltage

Block Diagram

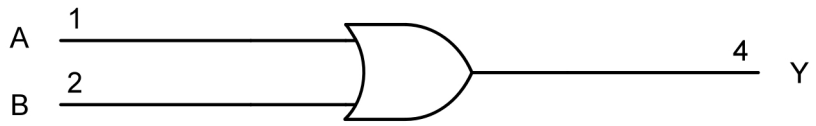


Figure2. Logic Symbol

Function Table

Input		Output
A	**B**	**Y**
L	L	L
L	H	H
H	L	H
H	H	H

Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage (VCC Pin)		-0.5 to 6.5	V
V_I	DC Input Voltage (1)		$-0.5 \le V_I \le 6.5$	V
V_O	DC Output Voltage Output in Higher or Low State		-0.5 to V_{CC} + 0.5	V
I_{IK}	DC Input Diode Current, V_I < GND		-50	mA
I_{OK}	DC Output Diode Current, V_O < GND, V_O > V_{CC}		±50	mA
I_O	DC Output Sink Current		±50	mA
I_{CC}	DC Supply Current Per Supply Pin		+100	mA
I_{GND}	DC Ground Current Per Supply Pin		-100	mA
T_{STG}	Storage Temperature Range		-65 to 150	°C
T_J	Max Junction Temperature		150	°C
V_{ESD} (2)	ESD Classification	Human Body Model	±4000	V
		Charged Device Model	±1000	
I_{LU} (2)	Latch Up Current Above V_{CC} and GND at 125°C		±100	mA

Stresses exceeding those listed in this table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Note1: I_O absolute maximum rating must be observed.

Note2: HBM tested per AEC-Q100-002(JEDEC JS-001);

Note3: CDM tested per AEC-Q100-011(JEDEC JS-002);

Note4: Latch Up Current Maximum Rating tested per AEC-Q100-004(JEDEC JESD78F).

Thermal Characteristics

Symbol	Package	Ratings	Value	Unit
$R_{\theta JA}$	SOT23-5	Thermal Characteristics, Thermal Resistance, Junction-to-Air	250	°C/W
P_D	SOT23-5	Power Dissipation in Still Air at 85°C	260	

Recommended Operating Conditions

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage Operating		1.65	5.5	V
	Date Retention		1.5	5.5	
V_I	DC Input Voltage		0	V_{CC}	V
V_O	DC Output Voltage (High or Low State)		0	V_{CC}	V
T_A	Operating Temperature Range		-40	125	°C
t_r, t_f	Input Rise and Fall Time	V_{CC} = 2.5V ± 0.2V	0	20	ns/V
		V_{CC} = 3.0V ± 0.3V	0	10	
		V_{CC} = 5.0V ± 0.5V	0	5	

Electrical Characteristics

DC Electrical Characteristics

Symbol	Parameter	Condition	V_{CC}(V)	T_A = 25°C			-40°C ≤ T_A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	
V_{IH}	High-Level Input Voltage		1.65~1.95 2.3~ 5.5	0.75V_{CC} 0.7V_{CC}			0.75V_{CC} 0.7V_{CC}		V
V_{IL}	Low-Level Input Voltage		1.65~1.95 2.3~ 5.5			0.25V_{CC} 0.3V_{CC}		0.25V_{CC} 0.3V_{CC}	V
V_{OH}	High-Level Output Voltage	I_{OH} = -100μA	1.65~5.5	V_{CC} - 0.1	V_{CC}		V_{CC} - 0.1		V
		I_{OH} = -4mA	1.65	1.29	1.52		1.29		
		I_{OH} = -8mA	2.3	1.9	2.1		1.9		
		I_{OH} = -12mA	2.7	2.2	2.4		2.2		
		I_{OH} = -24mA	3.0	2.3	2.5		2.3		
		I_{OH} = -32mA	4.5	3.8	4.0		3.8		
V_{OL}	Low-Level Output Voltage	I_{OL} = 100μA	1.65~5.5		0.0	0.1		0.1	V
		I_{OL} = 4mA	1.65		0.08	0.24		0.24	
		I_{OL} = 8mA	2.3		0.20	0.3		0.3	
		I_{OL} = 12mA	2.7		0.22	0.4		0.4	
		I_{OL} = 24mA	3.0		0.38	0.55		0.55	
		I_{OL} = 32mA	4.5		0.42	0.55		0.55	
I_{IN}	Input Leakage Current	V_I = 5.5V or GND	0~5.5			± 0.1		±1.0	μA
I_{OFF}	Power Off Leakage Current	V_I = 5.5V or V_O = 5.5V	0			1.0		10	μA
I_{CC}	Quiescent Supply Current	V_I = 5.5V or GND	5.5			1.0		10	μA

AC Electrical Characteristics

$t_r = t_f = 3ns$

Symbol	Parameter	Condition	V_{CC}(V)	T_A = 25°C			-40°C ≤ T_A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	
t_{PD}	Propagation Delay (Figure 3 and 4)	R_L = 1kΩ; C_L = 30pF	1.65~1.95	1.5	15.1	19.6	1.5	26.7	ns
		R_L = 500Ω; C_L = 30pF	2.3~2.7	1.0	8.2	10.7	1.0	12.1	
		R_L = 500Ω; C_L = 50pF	2.7	1.0	7.4	9.6	1.0	10.6	
		R_L = 500Ω; C_L = 50pF	3.0~3.6	1.0	6.7	8.7	1.0	10.2	
		R_L = 500Ω; C_L = 50pF	4.5~5.5	1.0	4.9	6.4	1.0	7.2	

Capacitance Characteristics

Symbol	Parameter	Condition	Typ	Unit
C_{IN}	Input Capacitance	V_{CC} = 5.5V, V_I = 0V or V_{CC}	2.5	pF
C_{PD}	Power Dissipation Capacitance (5)	10MHz, V_{CC} = 3.3V, V_I = 0V or V_{CC}	21	pF
		10MHz, V_{CC} = 5.5V, V_I = 0V or V_{CC}	21	

Note5: C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

AC Test Circuit

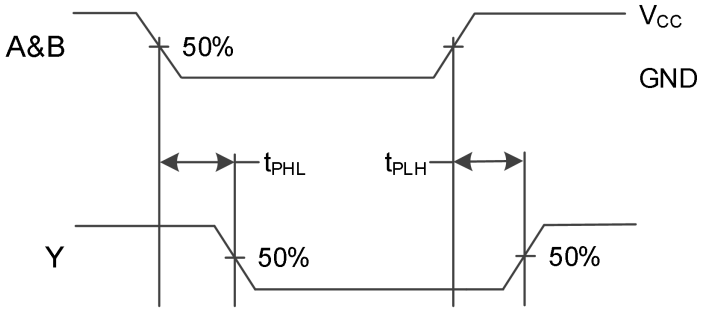


Figure3. Switching Waveform

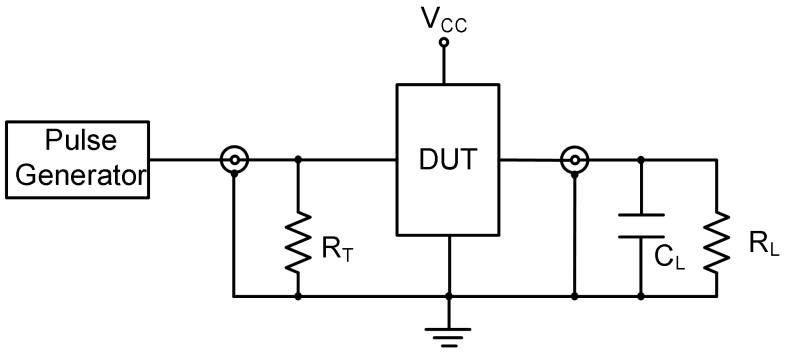
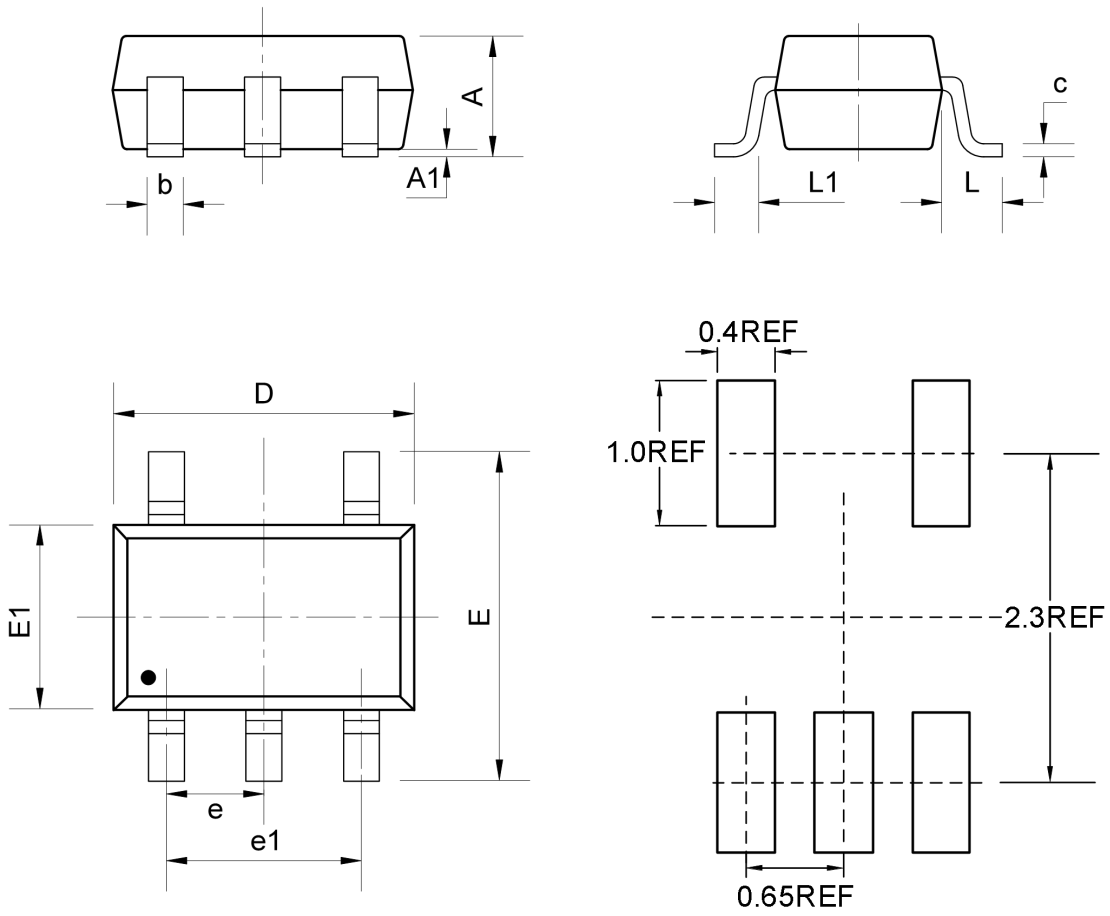


Figure4. Test Circuit

Package Dimension

SC70-5 (1.3mm × 2.1mm)

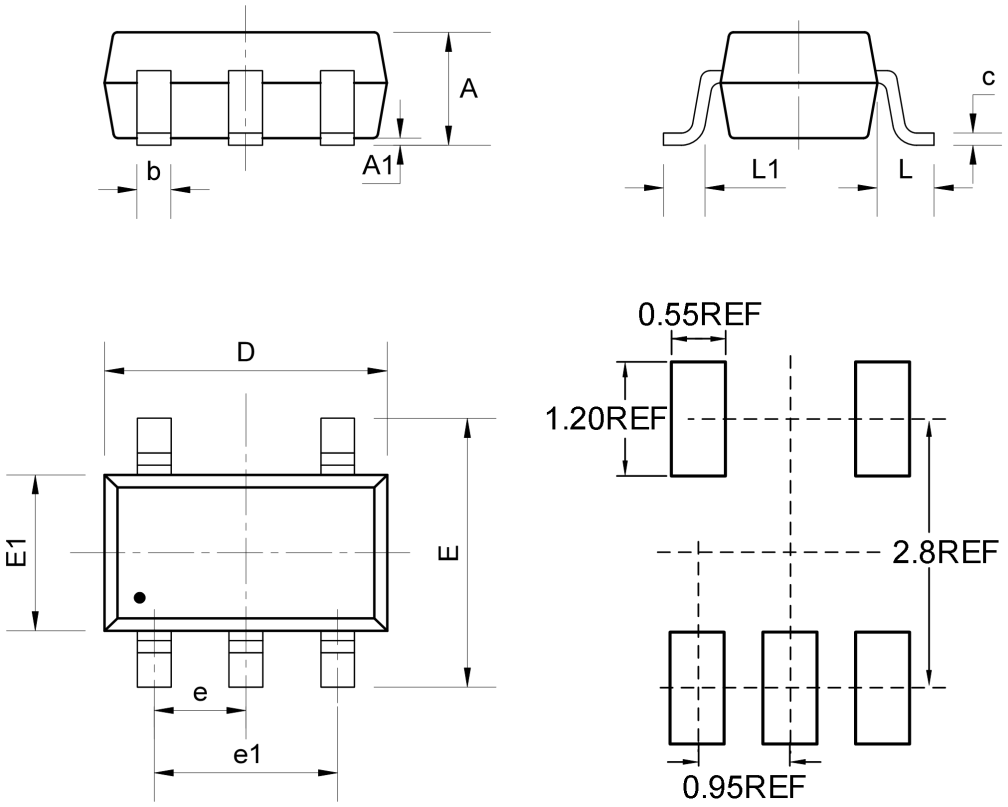


COMMON DIMENSIONS

(Unit: mm)

SYMBOL	MIN	NOM	MAX
A	-	-	1.10
A1	0.00	-	0.15
b	0.15	-	0.35
c	0.08	-	0.20
D	2.00	2.10	2.30
e	0.65BSC		
e1	1.30BSC		
E	2.15	2.30	2.50
E1	1.15	1.30	1.45
L	0.50REF		
L1	0.33REF		

SOT23-5 (1.6mm × 2.9mm)



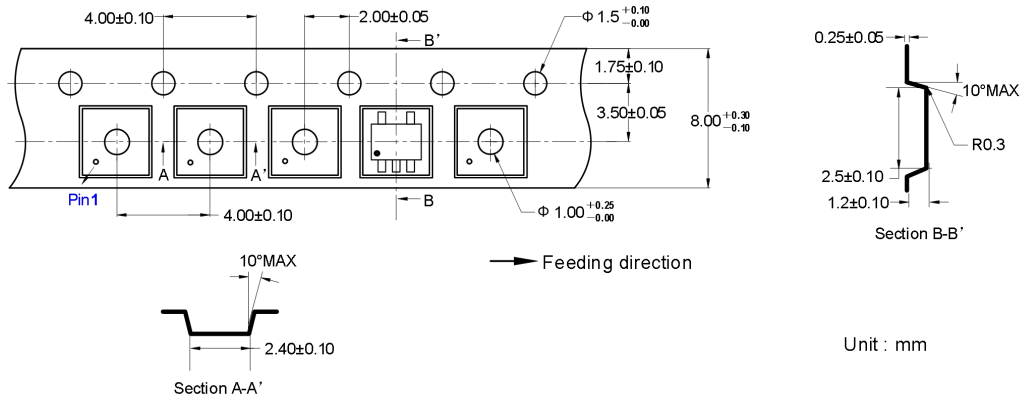
COMMON DIMENSIONS

(Unit: mm)

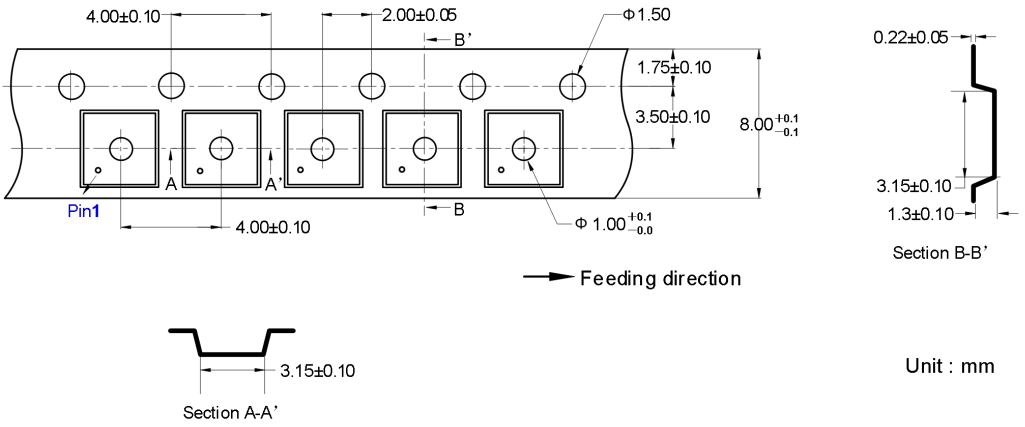
SYMBOL	MIN	NOM	MAX
A	-	-	1.45
A1	0.00	-	0.15
b	0.28	0.35	0.50
c	0.08	0.15	0.22
D	2.75	2.9	3.05
e	0.90	0.95	1.00
e1	1.80	1.90	2.00
E	2.60	2.80	3.00
E1	1.45	1.6	1.75
L	0.60REF		
L1	0.30	0.45	0.60

Tape Information

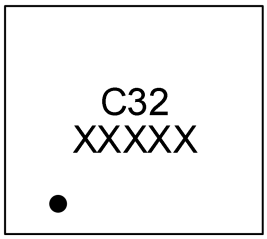
SC70-5 (1.3mm × 2.1mm)



SOT23-5 (1.6mm × 2.9mm)



Marking Information



ETQ74LVC1G32T

C32 = Part Number

XXXXX = Tracking Number

Revision History and Checking Table

Version	Date	Revision Item	Modifier	Function & Spec Checking	Package & Tape Checking
1.0	2017-10-23	Original Version	Ma yongjian	Ma yongjian	Liu jiaying
1.1	2019-07-18	Update AC Table and Device Information	Ma yongjian	Ma yongjian	Liu jiaying
1.2	2022-06-10	ESD Update	Shi bo	Shi bo	Zhu junli
1.3	2022-07-7	Update Thermal Characteristics	Shi bo	Shi bo	Zhu junli
1.4	2022-11-11	Update Typeset and Thermal Characteristics	Wu han	Shi bo	Zhu junli
1.5	2023-11-29	Update Typeset /ESD	Shi bo	Shi bo	Liu jiaying
1.6	2025-06-07	Add Packing Option	Yang xiaoxu	Yang xiaoxu	Liu jiaying
1.7	2025-10-15	Update Format	Wang anran	Yang xiaoxu	Liu jiaying
1.7.a	2025-12-16	Update Format and tpd, Add Tape and Marking	Chen mengyuan	Yang xiaoxu	Liu jiaying
1.7.b	2026-04-22	Update Format ,Package and Marking	Xu tao	Yang xiaoxu	Liu jiaying
1.7.c	2026-10-27	Add SC70-5 Package	Lu shaojie	Yang xiaoxu	Liu jiaying